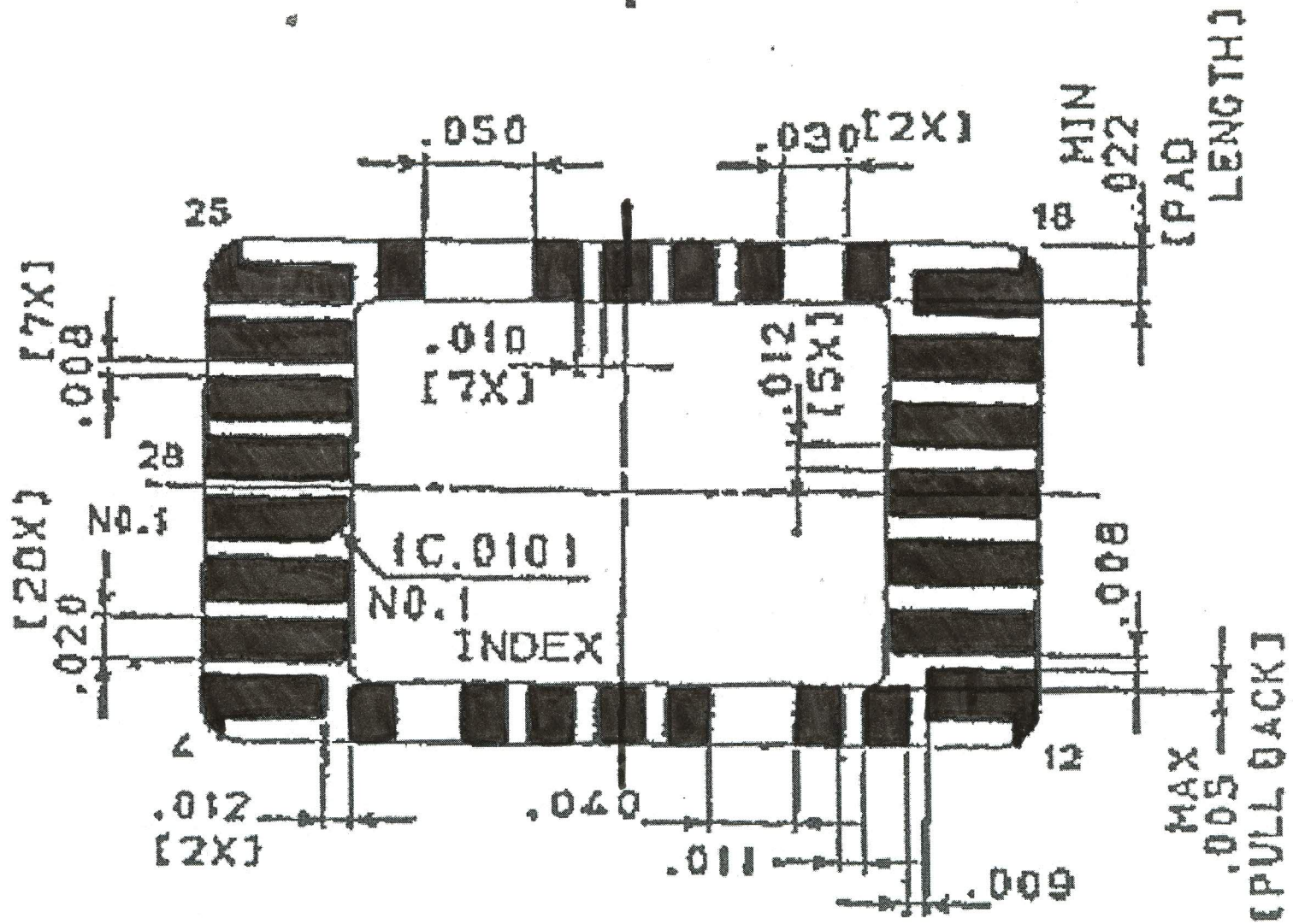


- NOTES: 1. GOLD PLATE 100μ INCHES MIN OVER 80μ INCHES MIN NICKEL.
 2. NO LEAD TO BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD.
 SEAL RING ISOLATED.
 3. LEAD RESISTANCE : 300mΩ MAX

IDENTIFIED
 PKG. NO. IRK28F1-5686A

3							
2							
1	CERAMIC	BLACK ALUMINA					
REV	DATE	BY	CHKD	APP'D	DESCRIPTION	DATE	
1		J. WASHINO			INDIAN TECHNICAL CERAMICS	8-5-1996	
		J. WASHINO			28 LEAD CHIP CARRIER	8-1-1996	
		J. WASHINO			28 LEAD CHIP CARRIER		
		J. WASHINO			28 LEAD CHIP CARRIER		
		J. WASHINO			28 LEAD CHIP CARRIER		

PART NO. SHEET 1 OF 1 M-1



B/G PAD DETAIL